

Amendments To The Abstract:

Please replace the Abstract with the following amended Abstract:

A method for heat-treating a plurality of microelectronic structures attached to a non-metallic substrate is disclosed. ~~Each of the plurality of microelectronic structures is comprised of a metallic material, and ones of the plurality of metallic microelectronic structures are insulated from other ones of the plurality of microelectronic structures. An application of the method is for heat treatment of resilient microstructures.~~—The method comprises the steps of: (a) placing the non-metallic substrate and the plurality of microelectronic structures in an oscillating electromagnetic field, whereby the plurality of microelectronic structures are heated by the oscillating electromagnetic field and the non-metallic substrate is essentially not heated by the oscillating electromagnetic field; (b) maintaining the non-metallic substrate and the plurality of microelectronic structures in the oscillating electromagnetic field until each of the plurality of microelectronic structures obtains a defined heat-treatment temperature substantially greater than an ambient temperature; (c) removing the non-metallic substrate and the plurality of microelectronic structures from the oscillating electromagnetic field; and (d) cooling the plurality of microelectronic structures to the ambient temperature.